



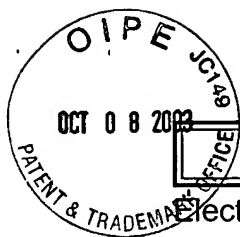
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Electronic Patent Application Submission
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EFS ID: 49076
Application ID: 10610016
Title of Invention: MAKING THERMALLY ENHANCED
CHIP SCALE LEAD ON CHIP
SEMICONDUCTOR PACKAGES
First Named Inventor: David McCann
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Confirmation number: 1207
Attorney Docket Number: AMKOR038C




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**TRANSMITTAL**

Electronic Version v1.1
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Title of Invention	MAKING THERMALLY ENHANCED CHIP SCALE LEAD ON CHIP SEMICONDUCTOR PACKAGES									
<p>Application Number: 10/610016 </p> <p>Date: 2003-10-03</p> <p>First Named Applicant: David R. McCann</p> <p>Confirmation Number: 1207</p> <p>Attorney Docket Number: AMKOR038C</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids2-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids2-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids2-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

MAKING THERMALLY ENHANCED CHIP SCALE LEAD ON
CHIP SEMICONDUCTOR PACKAGES

Application Number: 10/610016



Confirmation Number: 1207

First Named Applicant: David McCann

Attorney Docket Number: AMKOR038C

Art Unit: 2811

Search string: (5266834 or 5273938 or 5277972 or 5278446
or 5279029 or 5294897 or 5327008 or 5332864
or 5335771 or 5336931 or 5343076 or 5358905
or 5365106 or 5381042 or 5391439 or 5406124
or 5410180 or 5414299 or 5424576 or 5428248
or 5435057 or 5444301 or 5454905 or 5474958
or 5484274 or 5493151 or 5508556 or 5517056
or 5521429 or 5534467 or 5539251 or 5543657
or 5544412 or 5545923 or 5581122 or 5592019
or 5592025 or 5594274 or 5604376 or 5608267
or 5625222 or 5633528 or 5639990 or 5640047
or 5641997 or 5643433 or 5644169 or 5646831
or 5650663 or 5665996).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date